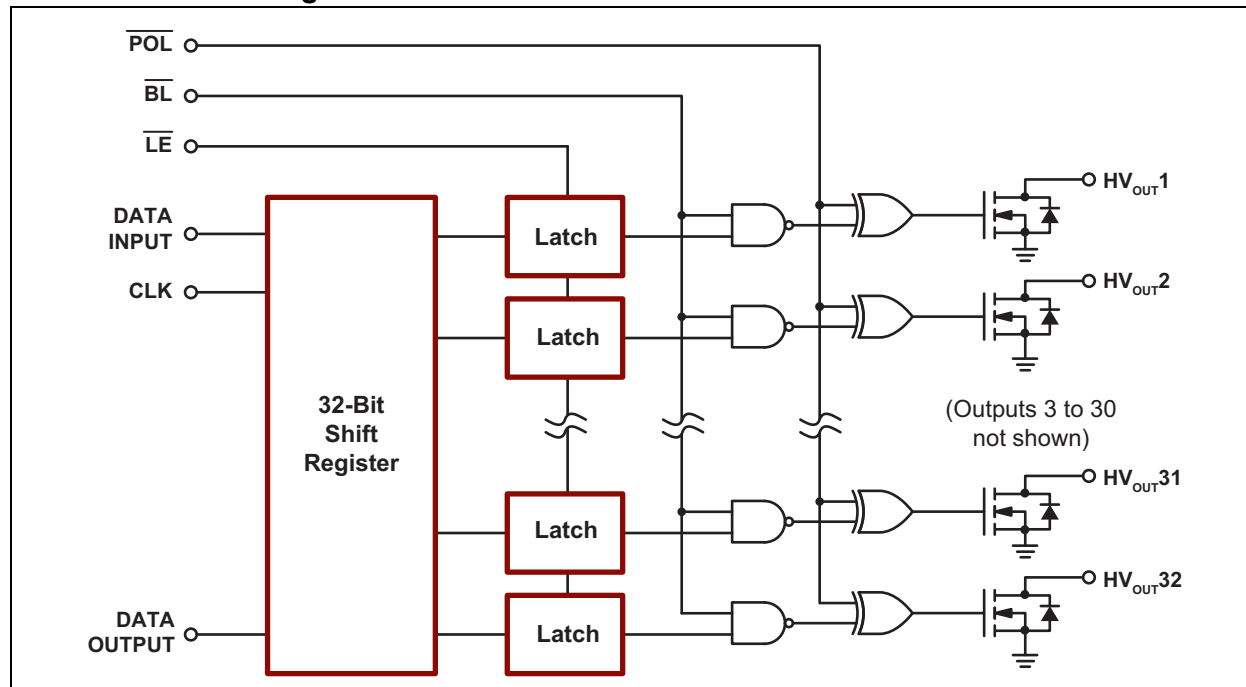


HV5623

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage, V_{DD} (Note 1)	–0.5V to +7V
Output Voltage, HV_{OUT} (Note 1)	–0.5V to +230V
Logic Input Levels (Note 1)	–0.5V to $V_{DD} + 0.5V$
Ground Current (Note 2)	1.5A
Maximum Junction Temperature, $T_{J(MAX)}$	+125°C
Storage Temperature, T_S	–65°C to +150°C
Continuous Total Power Dissipation:	
44-lead QFN (Note 3)	3.4W

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note 1: All voltages are referenced to V_{SS} .

2: Duty cycle is limited by the total power dissipated in the package.

3: 1 oz 4-layer 3" x 4" PCB

RECOMMENDED OPERATING CONDITIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Logic Supply Voltage	V_{DD}	4.5	—	5.5	V	
High-Voltage Output	HV_{OUT}	–0.3	—	+220	V	
High-Level Input Voltage	V_{IH}	0.8 V_{DD}	—	V_{DD}	V	
Low-Level Input Voltage	V_{IL}	0	—	0.2 V_{DD}	V	
Clock Frequency	f_{CLK}	—	—	16	MHz	
Operating Ambient Temperature	T_A	–40	—	+85	°C	

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Over recommended operating conditions unless otherwise noted.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
V_{DD} Supply Current	I_{DD}	—	—	25	mA	$f_{CLK} = 16$ MHz, $f_{DATA} = 8$ MHz
Quiescent V_{DD} Supply Current	I_{DDQ}	—	—	100	μA	$D_{IN} = 0V$, all input logic pins = 0V, all outputs off
Off-State Output Current	$I_{O(OFF)}$	—	—	10	μA	All outputs high, all switches parallel
High-Level Logic Input Current	I_{IH}	—	—	1	μA	$V_{IH} = V_{DD}$
Low-Level Logic Input Current	I_{IL}	—	—	–1	μA	$V_{IL} = 0V$
High-Level Output Data Out	V_{OH}	$V_{DD} - 1V$	—	—	V	$I_{DOUT} = -10$ mA
Low-Level Output Voltage	HV_{OUT}	V_{OL}	—	15	V	$I_{HVOUT} = +100$ mA
	Data Out		—	1	V	$I_{DOUT} = +10$ mA
HV_{OUT} Clamp Voltage	V_{OC}	—	—	–1.5	V	$I_{OL} = -100$ mA

AC ELECTRICAL CHARACTERISTICS

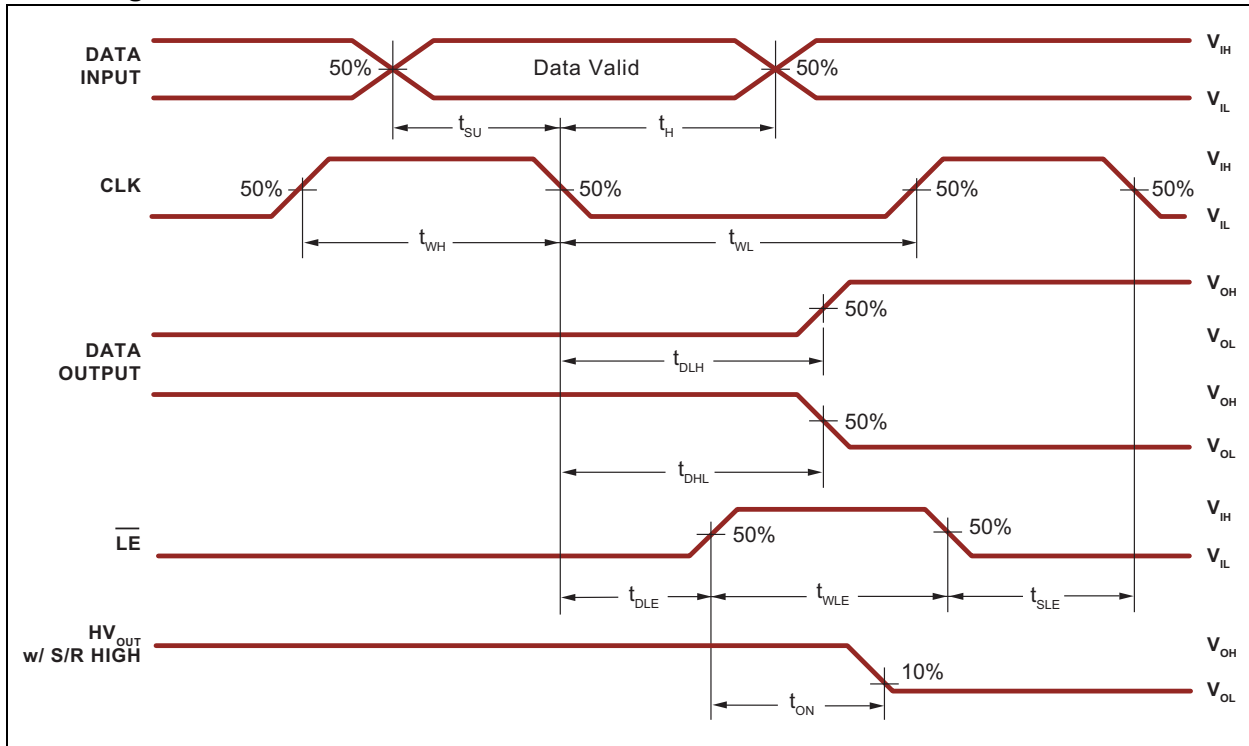
Electrical Specifications: $V_{DD} = 5V$, $T_J = 25^{\circ}C$						
Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Clock Frequency	f_{CLK}	—	—	16	MHz	
Clock Pulse Width, High or Low	t_{WL}, t_{WH}	31	—	—	ns	
Data Setup Time before CLK Falls	t_{SU}	25	—	—	ns	
Data Hold Time after CLK Falls	t_H	10	—	—	ns	
Turn-On Time, HV_{OUT} from Enable	t_{ON}	—	—	400	ns	$R_L = 2\text{ k}\Omega$ to V_{PP} maximum
Delay Time Clock to Data High to Low	t_{DHL}	—	—	35	ns	$C_L = 15\text{ pF}$
Delay Time Clock to Data Low to High	t_{DLH}	—	—	35	ns	$C_L = 15\text{ pF}$
Delay Time Clock to \overline{LE} Low to High	t_{DLE}	20	—	—	ns	
Width of \overline{LE} Pulse	t_{WLE}	20	—	—	ns	
\overline{LE} Setup Time before Clock Falls	t_{SLE}	20	—	—	ns	
Digital Logic Input Capacitance	C_{IN}	—	—	15	pF	

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-40	—	+85	$^{\circ}C$	
Maximum Junction Temperature	$T_{J(MAX)}$	—	—	+125	$^{\circ}C$	
Storage Temperature	T_S	-65	—	+150	$^{\circ}C$	
PACKAGE THERMAL RESISTANCE						
44-lead QFN	θ_{JA}	—	19	—	$^{\circ}C/W$	Note 1

Note 1: 1 oz 4-layer 3" x 4" PCB

Switching Waveforms



2.0 PIN DESCRIPTION

The details on the pins of HV5623 are listed in [Table 2-1](#). Refer to [Package Type](#) for the location of pins.

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	HV _{OUT} 22	High-voltage output
2	HV _{OUT} 21	High-voltage output
3	HV _{OUT} 20	High-voltage output
4	HV _{OUT} 19	High-voltage output
5	HV _{OUT} 18	High-voltage output
6	HV _{OUT} 17	High-voltage output
7	HV _{OUT} 16	High-voltage output
8	HV _{OUT} 15	High-voltage output
9	HV _{OUT} 14	High-voltage output
10	HV _{OUT} 13	High-voltage output
11	HV _{OUT} 12	High-voltage output
12	HV _{OUT} 11	High-voltage output
13	HV _{OUT} 10	High-voltage output
14	HV _{OUT} 9	High-voltage output
15	HV _{OUT} 8	High-voltage output
16	HV _{OUT} 7	High-voltage output
17	HV _{OUT} 6	High-voltage output
18	HV _{OUT} 5	High-voltage output
19	HV _{OUT} 4	High-voltage output
20	HV _{OUT} 3	High-voltage output
21	HV _{OUT} 2	High-voltage output
22	HV _{OUT} 1	High-voltage output
23	DATA OUT	Data output pin
24	NC	No internal connection
25	NC	No internal connection
26	NC	No internal connection
27	$\overline{\text{POL}}$	Inverts the polarity of the HV _{OUT} pins
28	CLK	Clock pin, Shift registers shift data on falling edge of input clock.
29	VSS	Reference voltage, usually ground
30	VDD	Logic supply voltage
31	$\overline{\text{LE}}$	Latch enable pin, data is shifted from Shift register to latches on logic input high.
32	DATA IN	Data input pin
33	$\overline{\text{BL}}$	Blanking pin sets all HV _{OUT} pins on or off depending upon state of polarity. See Table 3-2 .
34	N/C	No internal connection
35	HV _{OUT} 32	High-voltage output

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE (CONTINUED)

Pin Number	Pin Name	Description
36	HV _{OUT} 31	High-voltage output
37	HV _{OUT} 30	High-voltage output
38	HV _{OUT} 29	High-voltage output
39	HV _{OUT} 28	High-voltage output
40	HV _{OUT} 27	High-voltage output
41	HV _{OUT} 26	High-voltage output
42	HV _{OUT} 25	High-voltage output
43	HV _{OUT} 24	High-voltage output
44	HV _{OUT} 23	High-voltage output
Center Tab		Connect to VSS.

3.0 FUNCTIONAL DESCRIPTION

Follow the steps in [Table 3-1](#) to power up and power down the HV5623.

TABLE 3-1: POWER-UP AND POWER-DOWN SEQUENCE

Power-Up		Power-Down	
Step	Description	Step	Description
1	Connect ground.	1	Remove all inputs.
2	Apply V _{DD} .	2	Remove V _{DD} .
3	Set all inputs to a known state.	3	Disconnect ground.

TABLE 3-2: FUNCTION TABLE

Function	Inputs ¹					Outputs				
						Shift Register		High-Voltage Output		Data Out
	Data	CLK	$\overline{\text{LE}}$	$\overline{\text{BL}}$	$\overline{\text{POL}}$	1	2...32	1	2...32	
All On	X	X	X	L	L	Note 2	Note 2	On	On	Note 2
All Off	X	X	X	L	H	Note 2	Note 2	Off	Off	Note 2
Invert Mode	X	X	L	H	L	Note 2	Note 2	Note 2	Note 2	Note 2
Load S/R	H or L	↓	L	H	H	H or L	Note 2	Note 2	Note 2	Note 2
Load Latches	X	H or L	↑	H	H	Note 2	Note 2	Note 2	Note 2	Note 2
	X	H or L	↑	H	L	Note 2	Note 2	Note 2	Note 2	Note 2
Transparent Latch Mode	L	↓	H	H	H	L	Note 2	Off	Note 2	Note 2
	H	↓	H	H	H	H	Note 2	On	Note 2	Note 2

Note 1: H = High logic level
L = Low logic level
X = Don't care
↓ = Hight-to-low transition
↑ = Low-to-high transition

2: Dependent on previous stage's state before the last CLK ↓ or last $\overline{\text{LE}}$ high

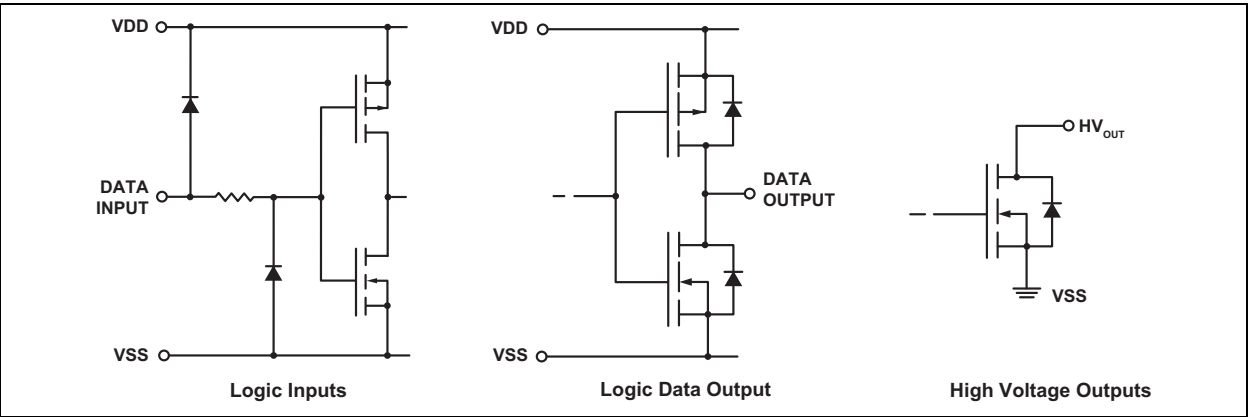
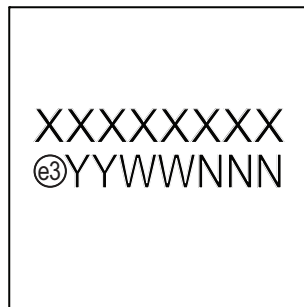


FIGURE 3-1: Input and Output Equivalent Circuits.

4.0 PACKAGE MARKING INFORMATION

4.1 Packaging Information

44-lead QFN



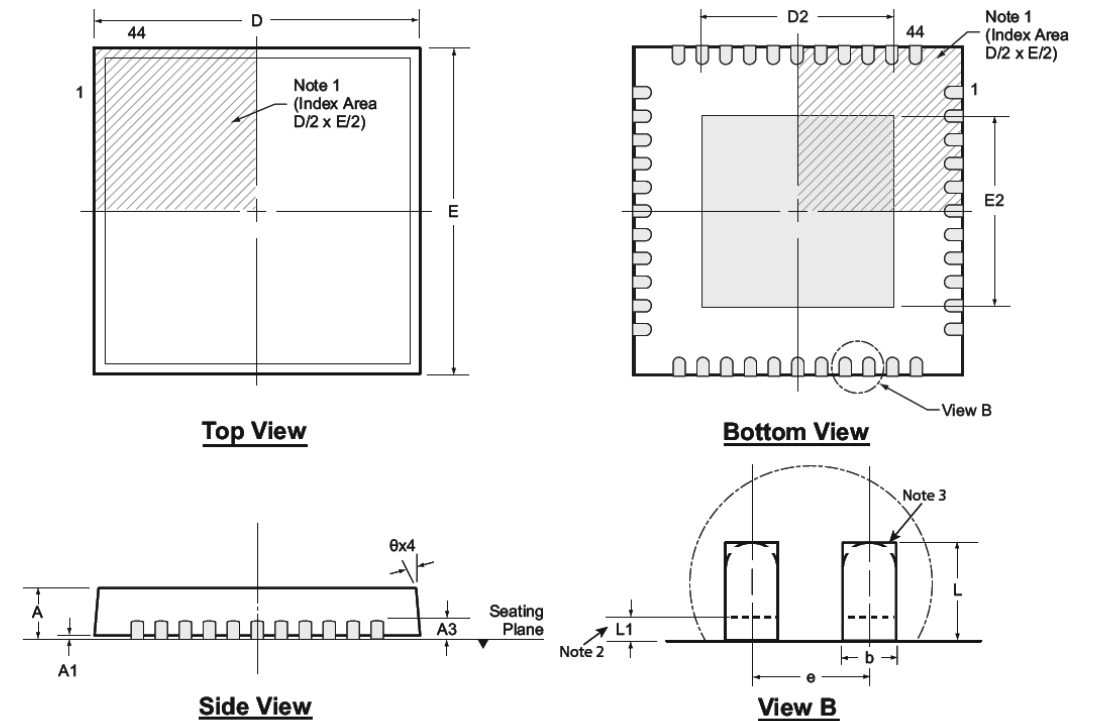
Example



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC [®] designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

44-Lead QFN Package Outline (K7)
7.00x7.00mm body, 0.80mm height (max), 0.50mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback ($L1$) may be present.
3. The inner tip of the lead may be either rounded or square.

Symbol		A	A1	A3	b	D	D2	E	E2	e	L	L1	θ
Dimension (mm)	MIN	0.70	0.00	0.20 REF	0.18	6.85*	5.00†	6.85*	5.00†	0.50 BSC	0.45†	0.00	0°
	NOM	0.75	0.02		0.25	7.00	5.15†	7.00	5.15†		0.55†	-	-
	MAX	0.80	0.05		0.30	7.15*	5.25†	7.15*	5.25†		0.65†	0.15	14°

JEDEC Registration MO-220, Variation WKKD-3, Issue K, June 2006

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

APPENDIX A: REVISION HISTORY

Revision A (July 2019)

- Converted Supertex Doc# DSFP-PIC18FXXXX to Microchip DS20005702A
- Changed the quantity of the 44-lead QFN K7 package from 280/Tray to 260/Tray
- Changed the quantity of the K7 M933 media type from 2000/Reel to 3000/Reel
- Removed the HVCMOS[®] Technology from the Features section
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.		XX		-	X	-	X
Device		Package Options			Environmental		Media Type
Device:	HV5623	=	32-Channel Serial-to-Parallel Converter with Open-Drain Outputs				
Package:	K7	=	44-lead (7x7) WQFN				
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package				
Media Type:	(blank)	=	260/Tray for a K7 Package				
	M933	=	3000/Reel for a K7 Package				

Examples:

 a) HV5623K7-G: 32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 260/Tray

 b) HV5623K7-G-M933: 32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 3000/Reel

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